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(54) **COMPONENT MOUNTING SUBSTRATE**

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ABSTRACT

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Provided is a component mount board having a structure capable of more reliably sensing a state of the component mount board being soaked in liquid. A component mount board 100 includes a board 10 having a base 11, a first conductive pattern 30 formed on the base 11, and a mount component 50 electrically connected to the first conductive pattern 30 and a second conductive pattern 40 forming a circuit 60 together with the first conductive pattern 30 in a complementary manner. A portion of the base 11 corresponding to the second conductive pattern 40 is a missing portion 12 where the base 11 is missing. The second conductive pattern 40 is soluble in liquid, or is weakened when becoming wet with liquid.

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